

# FH32P03G6

**P-Channel MOSFET**

## General Description

The FH32P03G6 is the highest performance trench P-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

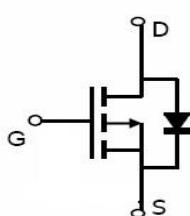
The FH32P03G6 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

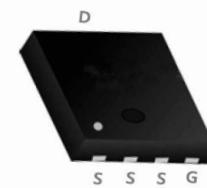
## Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

## General Features

- $V_{DS} = -30V$ ,  $I_D = -32A$
- $R_{DS(ON)} (\text{Typ}) 9 m\Omega @ V_{GS} = -10V$
- $R_{DS(ON)} (\text{Typ}) 14 m\Omega @ V_{GS} = -4.5V$
- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available


**Schematic diagram**

**Marking and Pin Assignment**

**PDFN3.3x3.3-8L top view**

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous (Note 1)	$I_D$	-32	A
Drain Current-Continuous( $T_C=100^\circ\text{C}$ )	$I_D (100^\circ\text{C})$	-15	A
Drain Current-Pulsed (Note 1/3)	$I_{DM}$	-85	A
Maximum Power Dissipation	$P_D$	29	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ\text{C}$

## Thermal Characteristic

Thermal Resistance,Junction-to-Case (Note 2)	$R_{\theta JC}$	3.43	$^\circ\text{C}/\text{W}$
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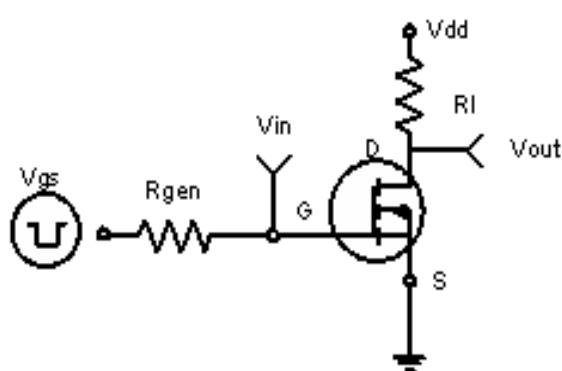
**Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.1	-1.5	-1.9	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-15\text{A}$	-	9	14	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-10\text{A}$	-	14	19	$\text{m}\Omega$
Gate resistance	$R_{\text{G}}$		-	5.4	-	$\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-15\text{A}$	16	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=-25\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	1870	-	PF
Output Capacitance	$C_{\text{oss}}$		-	309	-	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	228	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=-15\text{V}, I_{\text{D}}=-15\text{A}, V_{\text{GS}}=-10\text{V}, R_{\text{GEN}}=1\Omega$	-	13	-	nS
Turn-on Rise Time	$t_{\text{r}}$		-	10	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	27	-	nS
Turn-Off Fall Time	$t_{\text{f}}$		-	13	-	nS
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-20\text{A}, V_{\text{GS}}=-10\text{V}$	-	47.6	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	4.6	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	11.1	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-20\text{A}$	-	-	-1.2	V

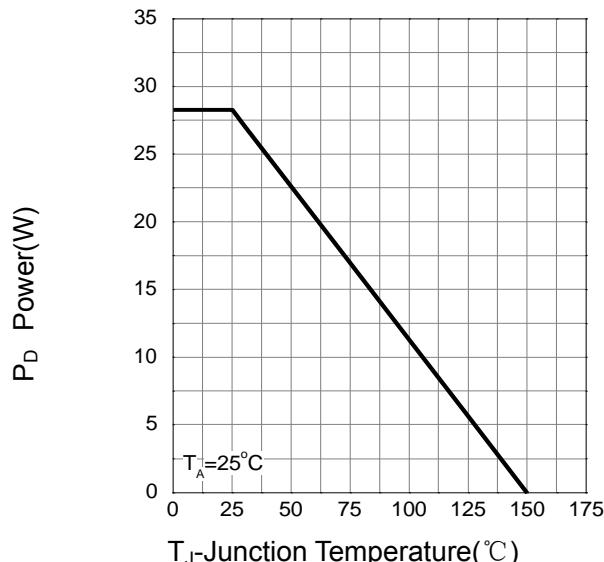
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

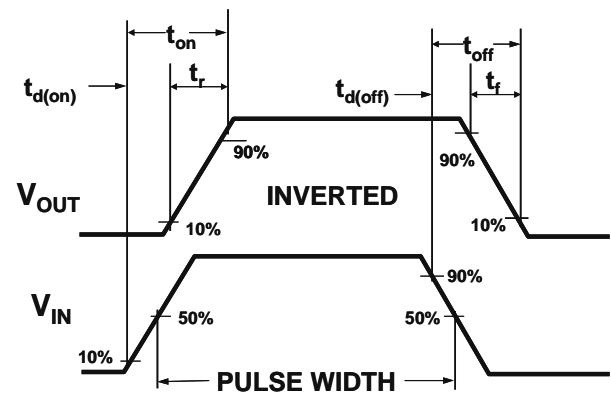
## Typical Electrical and Thermal Characteristics



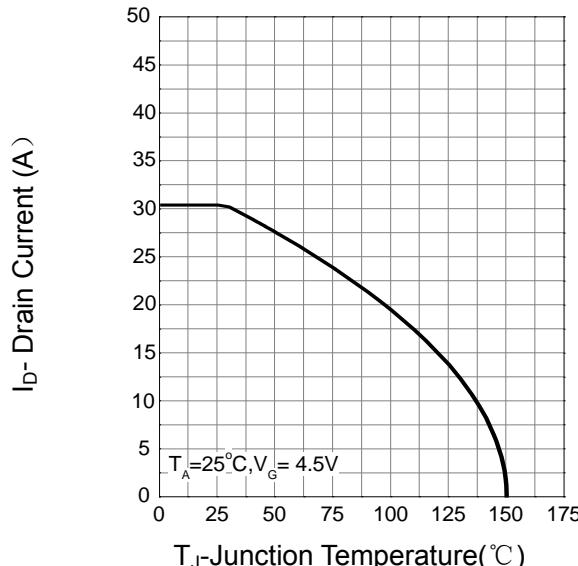
**Figure 1:Switching Test Circuit**



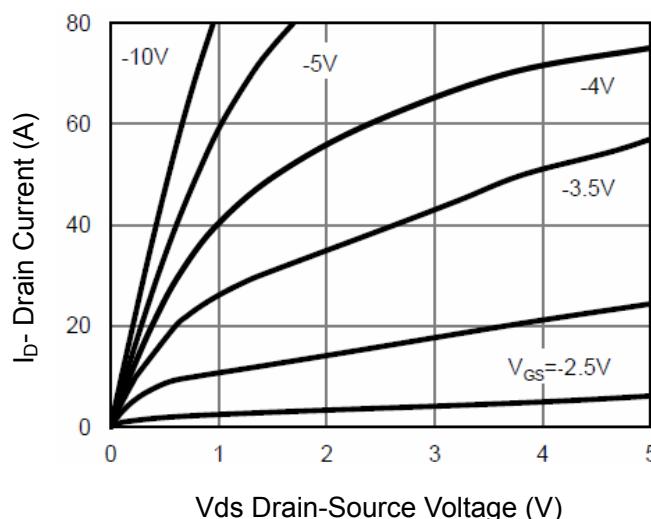
**Figure 3 Power Dissipation**



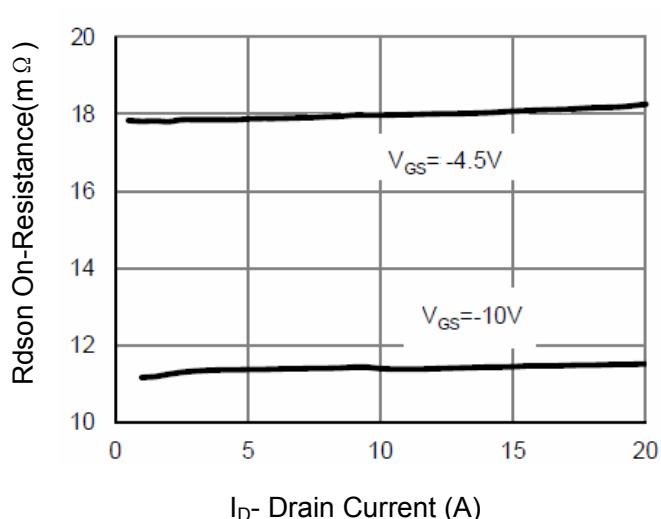
**Figure 2:Switching Waveforms**



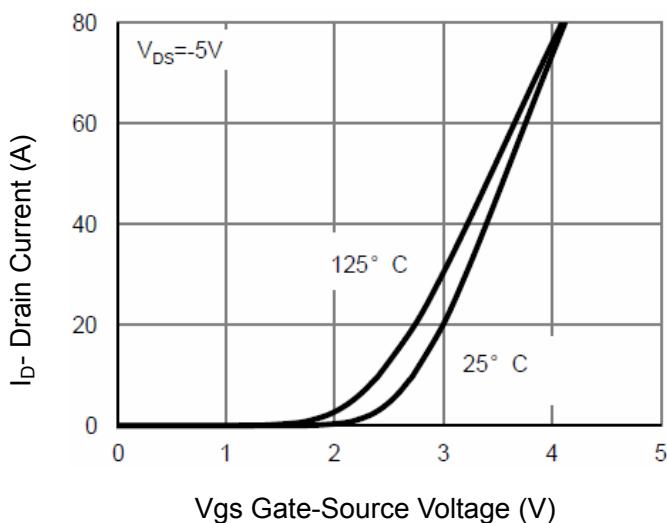
**Figure 4 Drain Current**



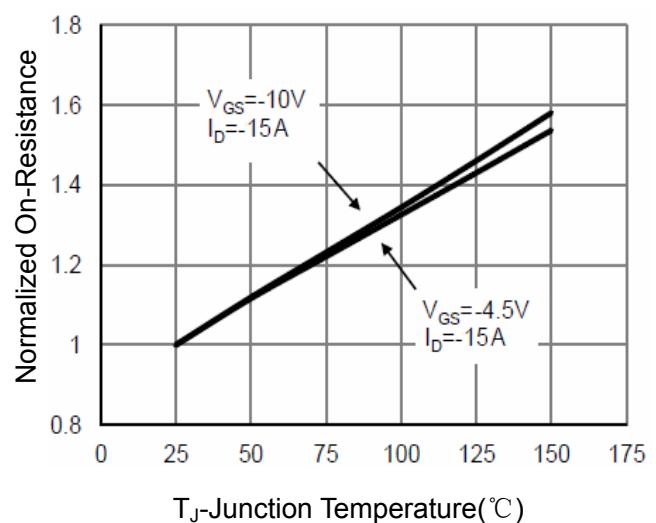
**Figure 5 Output Characteristics**



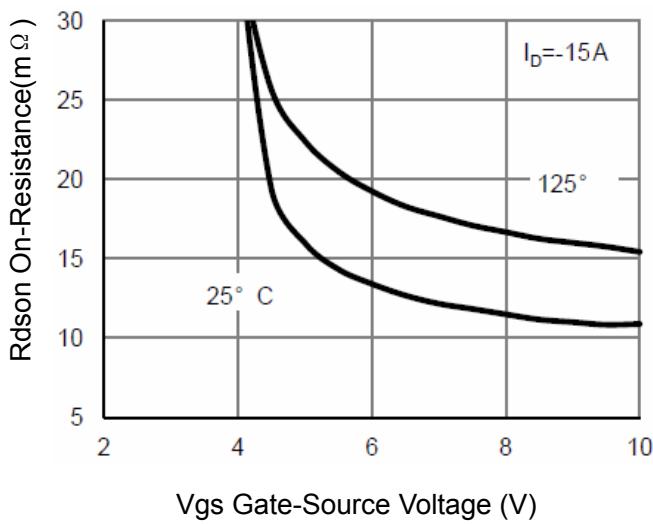
**Figure 6 Drain-Source On-Resistance**



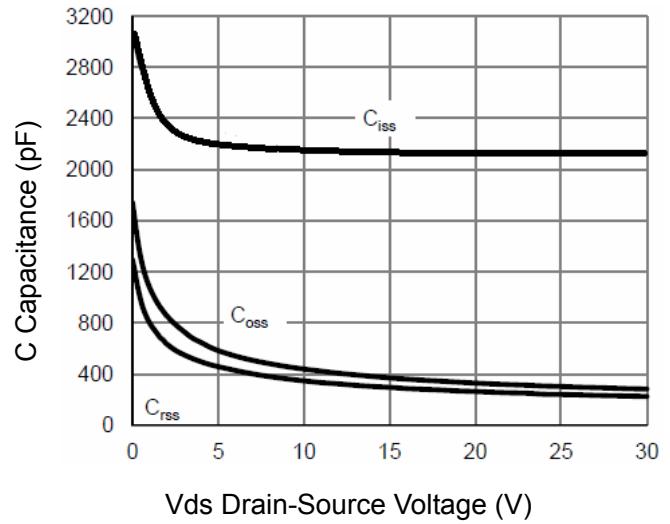
**Figure 7 Transfer Characteristics**



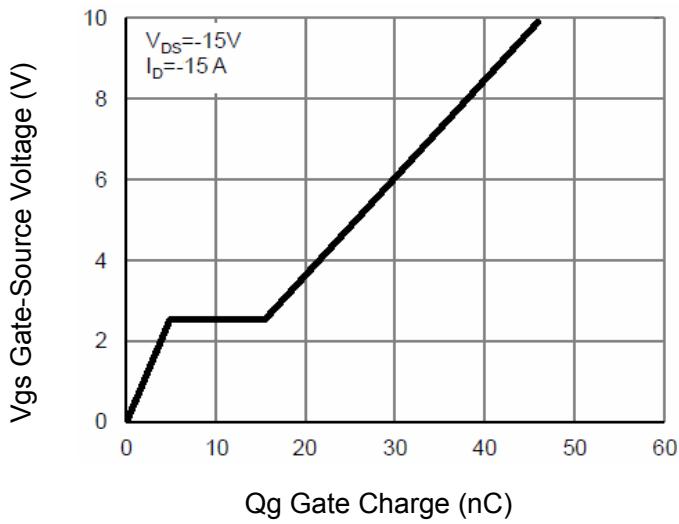
**Figure 8 Drain-Source On-Resistance**



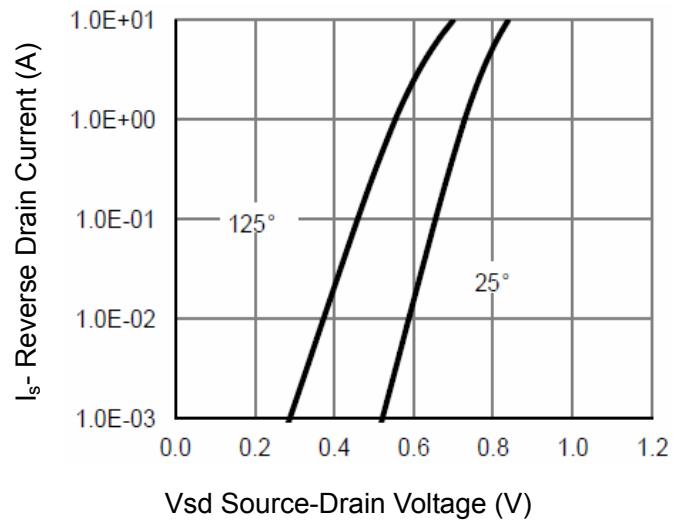
**Figure 9  $R_{DS(on)}$  vs  $V_{GS}$**



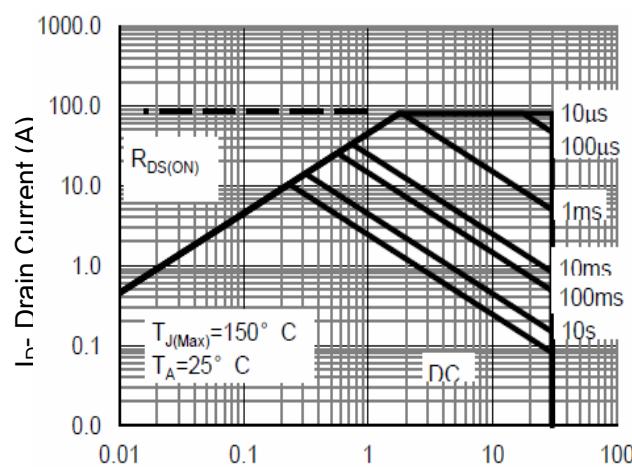
**Figure 10 Capacitance vs  $V_{DS}$**



**Figure 11 Gate Charge**

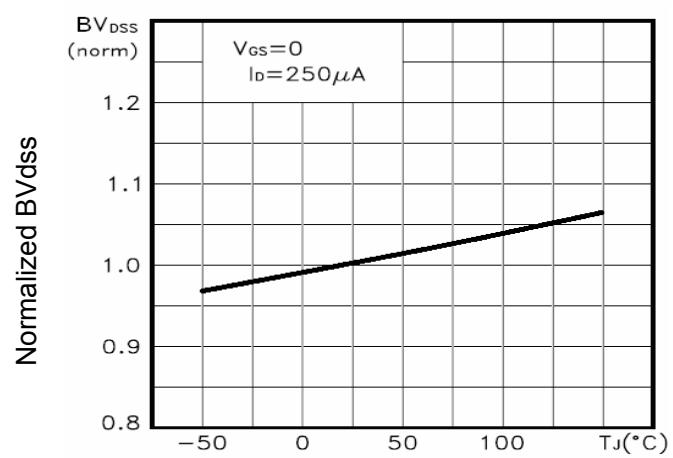


**Figure 12 Source-Drain Diode Forward**



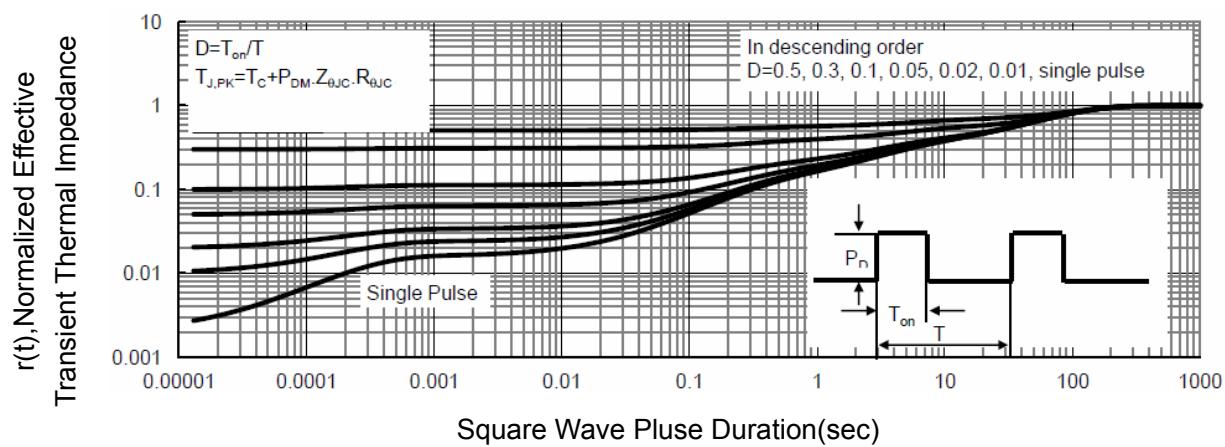
V<sub>DS</sub> Drain-Source Voltage (V)

**Figure 13 Safe Operation Area**



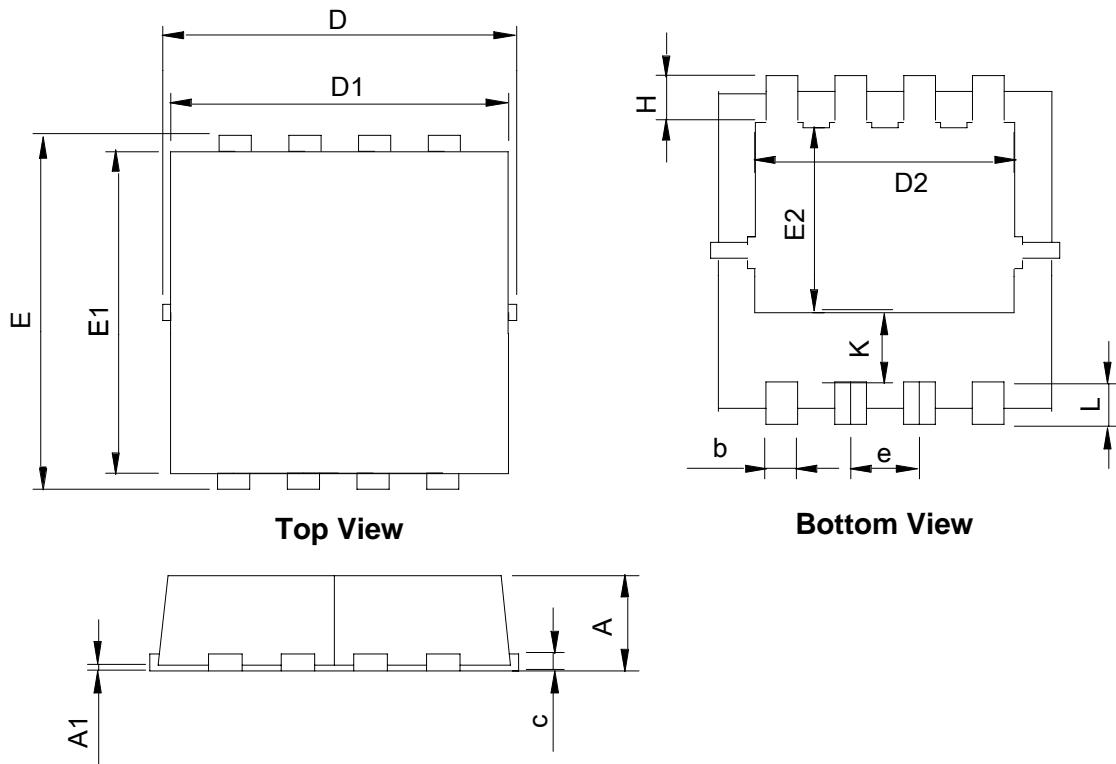
$T_J$ -Junction Temperature( $^\circ C$ )

**Figure 14  $BV_{DSS}$  vs Junction Temperature**



**Figure 15 Normalized Maximum Transient Thermal Impedance**

## Package Information : PDFN3.3x3.3-8L



SYMBOL	PDFN3.3x3.3-8L			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	1.00	0.028	0.039
A1	0.00	0.05	0.000	0.002
b	0.25	0.35	0.010	0.014
c	0.14	0.20	0.006	0.008
D	3.10	3.50	0.122	0.138
D1	3.05	3.25	0.120	0.128
D2	2.35	2.55	0.093	0.100
E	3.10	3.50	0.122	0.138
E1	2.90	3.10	0.114	0.122
e	0.65 BSC		0.026 BSC	
H	0.32	0.52	0.013	0.020
K	0.59	0.79	0.023	0.031
L	0.25	0.55	0.010	0.022